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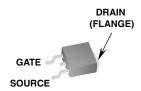


Data Sheet September 2010

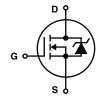
20A, 60V, 0.027 Ohm, N-Channel, Logic Level UltraFET® Power MOSFETs

Packaging





Symbol







Features

- Ultra Low On-Resistance
 - $r_{DS(ON)} = 0.023\Omega$, $V_{GS} = 10V$
 - $r_{DS(ON)} = 0.027\Omega$, $V_{GS} = 5V$
- · Simulation Models
 - Temperature Compensated PSPICE® and SABER™ Electriecal Models
 - Spice and SABER Thermal Impedance Models
 - www.fairchild.com
- · Peak Current vs Pulse Width Curve
- · UIS Rating Curve
- Switching Time vs R_{GS} Curves
- · Qualified to AEC Q101
- · RoHS Compliant

Ordering Information

PART NUMBER	PACKAGE	BRAND	
HUFA76429D3ST_F085	TO-252AA	76429D	

NOTE: When ordering, use the entire part number. Add the suffix T to obtain the variant in tape and reel, e.g., HUFA76429D3ST.

Absolute Maximum Ratings T_C = 25°C, Unless Otherwise Specified

	HUFA76429D3ST_F085	UNITS
Drain to Source Voltage (Note 1)	60	V
Drain to Gate Voltage (R _{GS} = 20kΩ) (Note 1)	60	V
Gate to Source Voltage	±16	V
Drain Current		
Continuous ($T_C=25^{\circ}C$, $V_{GS}=5V$)	20	Α
Continuous (T_C = 25°C, V_{GS} = 10V) (Figure 2)	20	Α
Continuous (T_C = 100°C, V_{GS} = 5V)	20	Α
Continuous (T_C = 100°C, V_{GS} = 4.5V) (Figure 2)	20	Α
Pulsed Drain Current	Figure 4	
Pulsed Avalanche RatingUIS	Figures 6, 17, 18	
Power Dissipation	110	W
Derate Above 25°C	0.74	W/oC
Operating and Storage Temperature	-55 to 175	oC
Maximum Temperature for Soldering		
Leads at 0.063in (1.6mm) from Case for 10sTL	300	°C
Package Body for 10s, See Techbrief TB334	260	°C
NOTES:		

^{1.} $T_J = 25^{\circ}C$ to $150^{\circ}C$.

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

This product has been designed to meet the extreme test conditions and environment demanded by the automotive industry. For a copy of the requirements, see AEC Q101 at: http://www.aecouncil.com/

Reliability data can be found at: http://www.mtp.fairchild.com/automotive.html.

All Fairchild semiconductor products are manufactured, assembled and tested under ISO9000 and QS9000 quality systems certification.

HUFA76429D3ST_F085

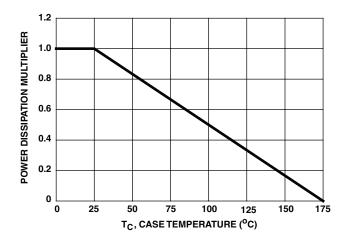
Electrical Specifications $T_C = 25^{\circ}C$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS		MIN	TYP	MAX	UNITS
OFF STATE SPECIFICATIONS						I	
Drain to Source Breakdown Voltage	BV _{DSS}	I _D = 250μA, V _{GS} = 0V (Figure 12)		60	-	-	V
		$I_D = 250 \mu A, V_{GS} = 0$	V , T _C = -40 ^o C (Figure 12)	55	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 55V, V _{GS} = 0	V	-	-	1	μΑ
		V _{DS} = 50V, V _{GS} = 0	$V_{DS} = 50V, V_{GS} = 0V, T_{C} = 150^{\circ}C$		-	250	μΑ
Gate to Source Leakage Current	I _{GSS}	V _{GS} = ±16V		-	-	±100	nA
ON STATE SPECIFICATIONS						I	
Gate to Source Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_{D} = 250$	μΑ (Figure 11)	1	-	3	V
Drain to Source On Resistance	r _{DS(ON)}	I _D = 20A, V _{GS} = 10V	' (Figures 9, 10)	-	0.0205	0.023	Ω
		I _D = 20A, V _{GS} = 5V	I _D = 20A, V _{GS} = 5V (Figure 9)		0.024	0.027	Ω
		I _D = 20A, V _{GS} = 4.5V (Figure 9)		-	0.025	0.029	Ω
THERMAL SPECIFICATIONS	1	1 33	<u> </u>	_1	1	1	1
Thermal Resistance Junction to Case	$R_{\theta JC}$	TO-251 and TO-252		-	-	1.36	°C/W
Thermal Resistance Junction to Ambient	$R_{\theta JA}$			-	-	100	°C/W
SWITCHING SPECIFICATIONS (VGS	= 4.5V)						
Turn-On Time	ton	$V_{DD} = 30V$, $I_{D} = 20A$ $V_{GS} = 4.5V$, $R_{GS} = 7.5\Omega$ (Figures 15, 21, 22)		-	-	220	ns
Turn-On Delay Time	t _d (ON)			-	13	-	ns
Rise Time	t _r			-	134	-	ns
Turn-Off Delay Time	t _{d(OFF)}			-	30	-	ns
Fall Time	t _f			-	55	-	ns
Turn-Off Time	tOFF			-	-	130	ns
SWITCHING SPECIFICATIONS (VGS	= 10V)					l	
Turn-On Time	ton	V _{DD} = 30V, I _D = 20A	<u> </u>	-	-	65	ns
Turn-On Delay Time	t _{d(ON)}	$V_{GS} = 10V, R_{GS} = 8.2\Omega$ (Figures 16, 21, 22)		-	7.7	-	ns
Rise Time	t _r			-	36	-	ns
Turn-Off Delay Time	t _{d(OFF)}				60	-	ns
Fall Time	t _f			-	56	-	ns
Turn-Off Time	tOFF				-	175	ns
GATE CHARGE SPECIFICATIONS						I	1
Total Gate Charge	Q _{g(TOT)}	V _{GS} = 0V to 10V	V _{DD} = 30V,	-	38	46	nC
Gate Charge at 5V	Q _{g(5)}	$V_{GS} = 0V \text{ to } 5V$ $V_{GS} = 0V \text{ to } 1V$ $I_{D} = 20A,$ $I_{g(REF)} = 1.0\text{mA}$ (Figures 14, 19, 20)		-	21	25	nC
Threshold Gate Charge	Q _{g(TH)}		-	1.3	1.6	nC	
Gate to Source Gate Charge	Q _{gs}		(. 190100 1 1, 10, 20)	-	3.8	-	nC
Gate to Drain "Miller" Charge	Q _{gd}			-	9.7	-	nC
CAPACITANCE SPECIFICATIONS	<u> </u>			1	1	1	
Input Capacitance	C _{ISS}	$V_{DS} = 25V, V_{GS} = 0$	V,	-	1480	-	pF
Output Capacitance	C _{OSS}	f = 1MHz		-	440	-	pF
Reverse Transfer Capacitance	C _{RSS}	(Figure 13)		-	90	-	pF

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	V _{SD}	I _{SD} = 20A	-	-	1.25	V
		I _{SD} = 10A	-	-	1.00	V
Reverse Recovery Time	t _{rr}	$I_{SD} = 20A$, $dI_{SD}/dt = 100A/\mu s$	-	-	80	ns
Reverse Recovered Charge	Q _{RR}	$I_{SD} = 20A$, $dI_{SD}/dt = 100A/\mu s$	-	-	230	nC

Typical Performance Curves



25 V_{GS} = 10V V_{GS} = 4.5V V_{GS} = 4.5V V_{GS} = 4.5V T_C, CASE TEMPERATURE (°C)

FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

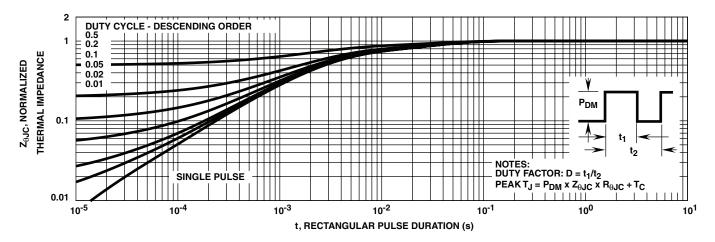


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

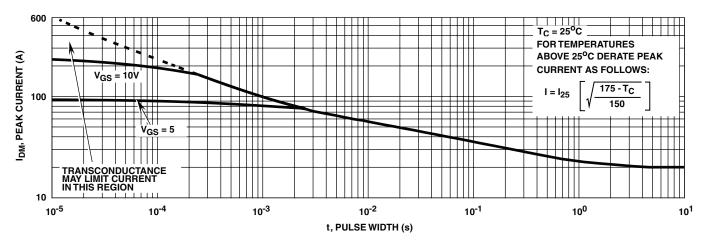


FIGURE 4. PEAK CURRENT CAPABILITY

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Typical Performance Curves (Continued)

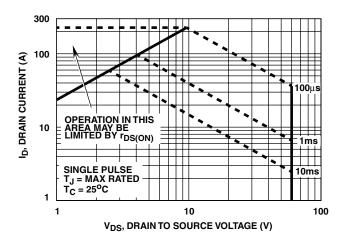


FIGURE 5. FORWARD BIAS SAFE OPERATING AREA

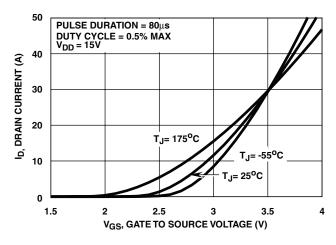


FIGURE 7. TRANSFER CHARACTERISTICS

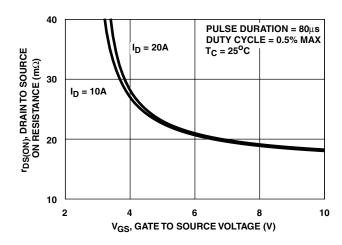
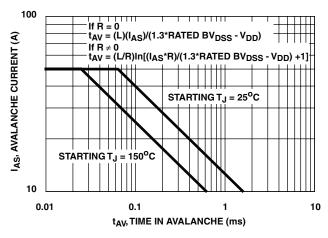


FIGURE 9. DRAIN TO SOURCE ON RESISTANCE vs GATE VOLTAGE AND DRAIN CURRENT



NOTE: Refer to Fairchild Application Notes AN9321 and AN9322.



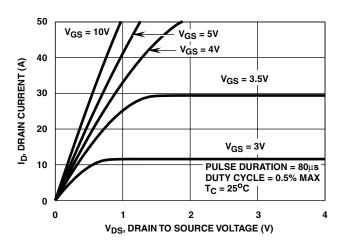


FIGURE 8. SATURATION CHARACTERISTICS

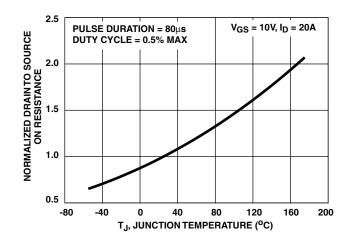


FIGURE 10. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

Typical Performance Curves (Continued)

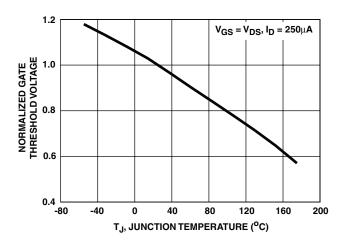


FIGURE 11. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

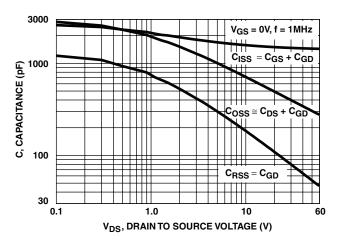


FIGURE 13. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE

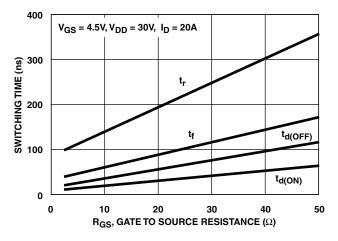


FIGURE 15. SWITCHING TIME vs GATE RESISTANCE

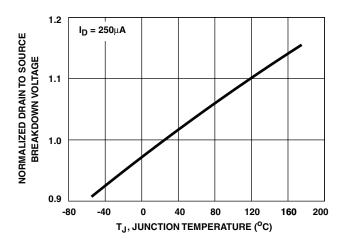
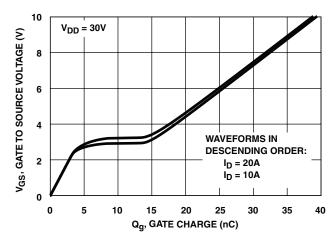


FIGURE 12. NORMALIZED DRAINTO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE



NOTE: Refer to Fairchild Application Notes AN7254 and AN7260.

FIGURE 14. GATE CHARGE WAVEFORMS FOR CONSTANT GATE CURRENT

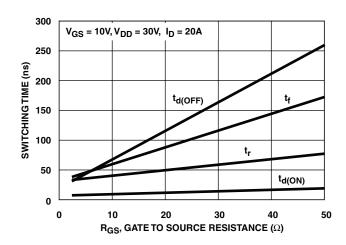


FIGURE 16. SWITCHING TIME vs GATE RESISTANCE

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Test Circuits and Waveforms

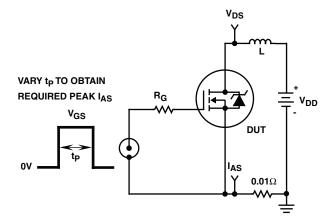


FIGURE 17. UNCLAMPED ENERGY TEST CIRCUIT

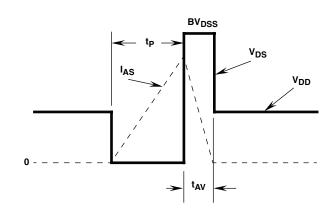


FIGURE 18. UNCLAMPED ENERGY WAVEFORMS

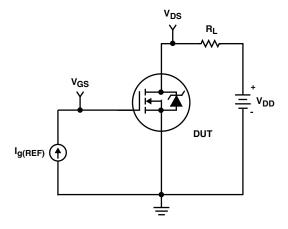


FIGURE 19. GATE CHARGE TEST CIRCUIT

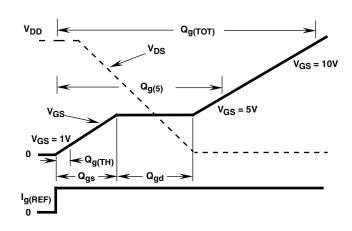


FIGURE 20. GATE CHARGE WAVEFORMS

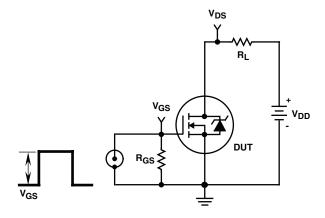


FIGURE 21. SWITCHING TIME TEST CIRCUIT

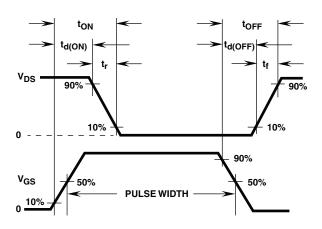


FIGURE 22. SWITCHING TIME WAVEFORM

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PSPICE Electrical Model

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.SUBCKT HUFA76429D3 2 1 3; rev 5 July 1999
```

```
CA 12 8 2.03e-9
CB 15 14 2.03e-9
CIN 6 8 1.39e-9
```

LDRAIN DPLCAP DRAIN 5 **DBODY 7 5 DBODYMOD** -02 DBREAK 5 11 DBREAKMOD 10 DPLCAP 10 5 DPLCAPMOD **RLDRAIN** ₹RSLC1 DBREAK \ 51 RSLC₂ FBRFAK 11 7 17 18 68 10 **ESLC** EDS 14 8 5 8 1 11 EGS 13 8 6 8 1 ESG 6 10 6 8 1 50 EVTHRES 6 21 19 8 1 17 18 DBODY RDRAIN <u>6</u> 8 **EBREAK** EVTEMP 20 6 18 22 1 **ESG EVTHRES** 16 21 19 **MWEAK** IT 8 17 1 **LGATE EVTEMP** 8 **RGATE** GATE MMED LDRAIN 2 5 1e-9 22 9 20 LGATE 1 9 5.42e-9 MSTRO RLGATE LSOURCE 3 7 4.16e-9 LSOURCE CIN SOURCE MMED 16 6 8 8 MMEDMOD 8 3 MSTRO 16 6 8 8 MSTROMOD **RSOURCE** MWEAK 16 21 8 8 MWEAKMOD **RLSOURCE** S1A اه S2A RBREAK 17 18 RBREAKMOD 1 RBREAK 13 8 12 F RDRAIN 50 16 RDRAINMOD 9.1e-3 14 13 15 17 18 RGATE 9 20 2.80 RLDRAIN 2 5 10 S₁B o SZB **≷** RVTEMP **RLGATE 1 9 54.2** 13 **RLSOURCE 3 7 41.6** CB 19 CA IT 14 RSLC1 5 51 RSLCMOD 1e-6 RSLC2 5 50 1e3 **VBAT** <u>6</u> 8 <u>5</u> **EGS EDS** RSOURCE 8 7 RSOURCEMOD 6.5e-3 RVTHRES 22 8 RVTHRESMOD 1 8 **RVTEMP 18 19 RVTEMPMOD 1** 22 **RVTHRES**

S1A 6 12 13 8 S1AMOD S1B 13 12 13 8 S1BMOD S2A 6 15 14 13 S2AMOD S2B 13 15 14 13 S2BMOD

VBAT 22 19 DC 1

ESLC 51 50 VALUE={(V(5,51)/ABS(V(5,51)))*(PWR(V(5,51)/(1e-6*117),3))}

```
.MODEL DBODYMOD D (IS = 1.25e-12 IKF = 10 RS = 8.40e-3 TRS1 = 2.05e-3 TRS2 = 3.85e-6 CJO = 1.68e-9 TT = 4.90e-8 M = 0.48 XTI = 4.35)
.MODEL DBREAKMOD D (RS = 1.68e-1 TRS1 = 1e-3 TRS2 = -1e-6)
.MODEL DPLCAPMOD D (CJO = 1.28e-9 IS = 1e-30 N = 10 M = 0.8)
MODEL MMEDMOD NMOS (VTO = 1.98 KP = 3.2 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u RG = 2.80)
MODEL MSTROMOD NMOS (VTO = 2.30 KP = 52 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u)
.MODEL MWEAKMOD NMOS (VTO = 1.72 KP = 0.08 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u RG = 28.0 RS = 0.1)
.MODEL RBREAKMOD RES (TC1 = 1.15e-3 TC2 = -5.40e-7)
.MODEL RDRAINMOD RES (TC1 = 7.85e-3 TC2 = 1.95e-5)
MODEL RSLCMOD RES (TC1 = 4.97e-3 TC2 = 5.05e-6)
.MODEL RSOURCEMOD RES (TC1 = 1.5e-3 TC2 = 1e-6)
.MODEL RVTHRESMOD RES (TC1 = -1.85e-3 TC2 = -4.48e-6)
.MODEL RVTEMPMOD RES (TC1 = -1.92e-3 TC2 = 9.50e-7)
.MODEL S1AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -6.2 VOFF= -2.4)
.MODEL S1BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -2.4 VOFF= -6.2)
.MODEL S2AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -1.1 VOFF= 0.5)
.MODEL S2BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = 0.5 VOFF= -1.1)
```

.ENDS

NOTE: For further discussion of the PSPICE model, consult **A New PSPICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options**; IEEE Power Electronics Specialist Conference Records, 1991, written by William J. Hepp and C. Frank Wheatley.

SABER Electrical Model

```
REV 5 July 1999
template HUFA76429d3 n2,n1,n3
electrical n2,n1,n3
var i iscl
d..model dbodymod = (is = 1.25e-12, cjo = 1.68e-9, tt = 4.90e-8, xti = 4.35, m = 0.48)
d..model dbreakmod = ()
d..model dplcapmod = (cjo = 1.28e-9, is = 1e-30, n = 10, m = 0.8)
m..model mmedmod = (type=_n, vto = 1.98, kp = 3.2, is = 1e-30, tox = 1)
m..model mstrongmod = (type=_n, vto = 2.30, kp = 52, is = 1e-30, tox = 1)
m..model mweakmod = (type=_n, vto = 1.72, kp = 0.08, is = 1e-30, tox = 1)
                                                                                                                               LDRAIN
sw_vcsp..model s1amod = (ron = 1e-5, roff = 0.1, von = -6.2, voff = -2.4)
                                                                                  DPLCAP
                                                                                                                                          DRAIN
sw_vcsp..model s1bmod = (ron = 1e-5, roff = 0.1, von = -2.4, voff = -6.2)
                                                                              10
sw_vcsp..model s2amod = (ron = 1e-5, roff = 0.1, von = -1.1, voff = 0.5)
                                                                                                                               RLDRAIN
sw_vcsp..model s2bmod = (ron = 1e-5, roff = 0.1, von = 0.5, voff = -1.1)
                                                                                              RSLC1
                                                                                                          RDBREAK
c.ca n12 n8 = 2.03e-9
                                                                               RSLC2
c.cb n15 n14 = 2.03e-9
                                                                                                                   72
                                                                                                                               RDBODY
                                                                                                ISCL
c.cin n6 n8 = 1.39e-9
                                                                                                            DBREAK
                                                                                              50
d.dbody n7 n71 = model=dbodymod
                                                                                              RDRAIN
d.dbreak n72 n11 = model=dbreakmod
                                                                            <u>6</u>
8
                                                                      ESG
                                                                                                                    11
d.dplcap n10 n5 = model=dplcapmod
                                                                                  EVTHRES
                                                                                              21
                                                                                     1<u>9</u>
i.it n8 n17 = 1
                                                                                                             MWEAK
                                                  LGATE
                                                                    EVTEMP
                                                                                                                               DBODY
                                                            RGATE
                                          GATE
                                                                                                ı
I.ldrain n2 n5 = 1e-9
                                                                                                    MMED
                                                                   20
I.lgate n1 n9 = 5.42e-9
                                                                                         di—mstrc
                                                  RLGATE
I.Isource n3 n7 = 4.16e-9
                                                                                                                               LSOURCE
                                                                                        CIN
                                                                                                                                          SOURCE
                                                                                                  8
m.mmed n16 n6 n8 n8 = model=mmedmod, l=1u, w=1u
m.mstrong n16 n6 n8 n8 = model=mstrongmod, l=1u, w=1u
                                                                                                             RSOURCE
m.mweak n16 n21 n8 n8 = model=mweakmod, l=1u, w=1u
                                                                                                                              RLSOURCE
                                                                     S1A o
res.rbreak n17 n18 = 1, tc1 = 1.15e-3, tc2 = -5.40e-7
                                                                                                                 RBREAK
                                                                         13
8
                                                                              14
13
                                                                                       15
res.rdbody n71 n5 = 8.40e-3, tc1 = 2.05e-3, tc2 = 3.85e-6
res.rdbreak n72 n5 = 1.68e-1, tc1 = 1.00e-3, tc2 = -1.00e-6
res.rdrain n50 n16 = 9.10e-3, tc1 = 7.85e-3, tc2 = 1.95e-5
                                                                     S1B
                                                                               o SŽB
                                                                                                                             RVTEMP
res.rgate n9 n20 = 2.80
                                                                            13
                                                                                       СВ
                                                                                                                             19
                                                              CA
res.rldrain n2 n5 = 10
                                                                                                            ΙT
                                                                                              14
res.rlgate n1 n9 = 54.2
                                                                                                                              VBAT
res.rlsource n3 n7 = 41.6
                                                                        EGS
                                                                                    EDS
res.rslc1 n5 n51 = 1e-6, tc1 = 4.97e-3, tc2 = 5.05e-6
                                                                                                          8
res.rslc2 n5 n50 = 1e3
res.rsource n8 n7 = 6.5e-3, tc1 = 1.5e-3, tc2 = 1e-6
                                                                                                                 RVTHRES
res.rvtemp n18 n19 = 1, tc1 = -1.92e-3, tc2 = 9.50e-7
res.rvthres n22 n8 = 1, tc1 = -1.85e-3, tc2 = -4.48e-6
spe.ebreak n11 n7 n17 n18 = 68.10
spe.eds n14 n8 n5 n8 = 1
spe.egs n13 n8 n6 n8 = 1
spe.esg n6 n10 n6 n8 = 1
spe.evtemp n20 n6 n18 n22 = 1
spe.evthres n6 n21 n19 n8 = 1
sw_vcsp.s1a n6 n12 n13 n8 = model=s1amod
sw_vcsp.s1b n13 n12 n13 n8 = model=s1bmod
sw_vcsp.s2a n6 n15 n14 n13 = model=s2amod
sw_vcsp.s2b n13 n15 n14 n13 = model=s2bmod
v.vbat n22 n19 = dc=1
equations {
i (n51->n50) +=iscl
iscl: v(n51,n50) = ((v(n5,n51)/(1e-9+abs(v(n5,n51))))*((abs(v(n5,n51)*1e6/117))**3))
```

SPICE Thermal Model

REV 26 July 1999

HUFA76429D3

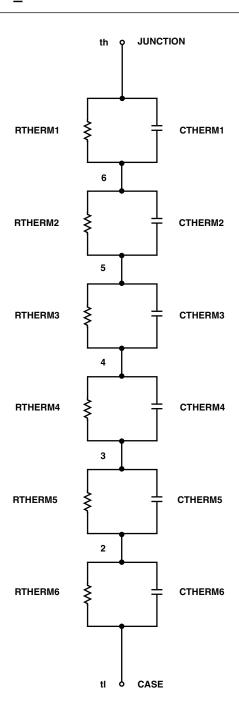
CTHERM1 th 6 2.45e-3 CTHERM2 6 5 8.15e-3 CTHERM3 5 4 7.40e-3 CTHERM4 4 3 7.45e-3 CTHERM5 3 2 1.01e-2 CTHERM6 2 tl 7.49e-2

RTHERM1 th 6 9.00e-3 RTHERM2 6 5 1.80e-2 RTHERM3 5 4 9.15e-2 RTHERM4 4 3 2.43e-1 RTHERM5 3 2 3.50e-1 RTHERM6 2 tl 3.62e-1

SABER Thermal Model

SABER thermal model HUFA76429D3

```
template thermal_model th tl thermal_c th, tl { ctherm.ctherm1 th 6=2.45e-3 ctherm.ctherm2 6.5=8.15e-3 ctherm.ctherm3 5.4=7.40e-3 ctherm.ctherm4 4.3=7.45e-3 ctherm.ctherm5 3.2=1.01e-2 ctherm.ctherm6 2.11=7.49e-2 rtherm.rtherm1 th 6=9.00e-3 rtherm.rtherm2 6.5=1.80e-2 rtherm.rtherm3 5.4=9.15e-2 rtherm.rtherm4 4.3=2.43e-1 rtherm.rtherm5 3.2=3.50e-1 rtherm.rtherm6 2.11=3.62e-1
```







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